



PCB LAYOUT

特性: Specifications:

电气: Electrical:

1. 接触阻抗: Contact Resistance: 30 milliohms MAX
2. 耐电压: Dielectnic With Standing Voitage: 500 V AC AT Sea Level
3. 绝缘阻抗: Insulation Resistance: 1000 MEGA ohms MIN

机构: Mechanical:

1. 结合力: Mating Force: 35 N MAX 最大 35 N
2. 拔出力: Unmating Force: 8 N MIN 最少 8 N

材料: Matorial:

1. 塑胶: PBT.
2. 端子: Contact: C2680
3. 外壳: Shell: SPCC

电镀: Finish:

1. 端子: Contact:Piated Gold in Mating Area:
Tin/Lead On Solder Talls. 接触点镀金, 脚镀锡
2. 外壳: Shell:
Nickel Plating . 镀镍



深圳市华宇创精密电子有限公司

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| TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5' | DRAWN BY : 陈一鸣 | DATE : 2014-02-23 | PART NAME: USB AF 双层弯脚半包双弹 |
| | CHECKED BY: 马跃 | DATE : 2014-02-23 | PART NO. HYC02-USBA08-155 |
| UNIT: mm [inch] SCALE:1:1 SIZE: A4 | APPROVED BY: 邱敏 | DATE : 2014-02-23 | MOLD NO. |
| | | | DRAW NO: HYC-2605061431 |
| | | | SHEET NO. 1 OF 1 |